

**PMP9579 Rev A Bill Of Materials**

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
PCB	1		Printed Circuit Board		PMP9579_REVA	Any
C1	1	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, C0G/NP0, 0402	0402	C1005X7R1H104K	TDK
C2, C7, C8	3	47uF	CAP, CERM, 47uF, 6.3V, +/-20%, X5R, 1206	1206	C3216X5R0J476M	TDK
C3	1	2.2uF	CAP, CERM, 2.2uF, 16V, +/-10%, X5R, 0402	0402	C1005X5R1C225K050BC	TDK
C5	1	0.01uF	CAP, CERM, 0.01uF, 25V, +/-10%, X8R, 0402	0402	C1005X8R1E103K	TDK
C6	1	10uF	CAP, CERM, 10uF, 10V, +/-20%, X5R, 0603	0603	C1608X5R1A106M	TDK
C9	1	0.047uF	CAP, CERM, 0.047uF, 6.3V, +/-10%, X7R, 0402	0402	GRM155R70J473KA01D	MuRata
D1	1	20V	Diode, Schottky, 20V, 2A, SMA	SMA	B220A-13-F	Diodes Inc.
D2	1	5.1V	Diode, Zener, 5.1V, 300mW, SOD-523	SOD-523	BZT52C5V1T-7	Diodes Inc.
J1	1		Header, 100mil, 2x1, Gold, R/A, TH	2x1 R/A Header	TSW-102-08-G-S-RA	Samtec
J2	1		Header, 2x1, 200mil, Gold R/A, TH	7.62x2.54x5.84 mm	TSW-202-08-G-S-RA	Samtec
L1	1	3.3uH	Coupled inductor, 4.7uH, 2.2A, 0.111 ohm, +/-20%, SMD	4.8x4.8x2.9mm	LPD5030-472ME	Coilcraft
L2	1	220 ohm	2.2A Ferrite Bead, 220 ohm @ 100MHz, SMD	0603	MPZ1608S221A	TDK
R1, R2	2	1.00k	RES, 1.00k ohm, 1%, 0.063W, 0402	0402	CRCW04021K00FKED	Vishay-Dale
R5	1	169	RES, 169 ohm, 1%, 0.063W, 0402	0402	CRCW0402169RFKED	Vishay-Dale
R6	1	51	RES, 51 ohm, 5%, 0.063W, 0402	0402	CRCW040251R0JNED	Vishay-Dale
U1	1		4.5V TO 28V INPUT, 3A OUTPUT, SYNCHRONOUS STEP DOWN SWIFT CONVERTER, DRC0010J	DRC0010J	TPS54336DRC	Texas Instruments

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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